Welcome to your new journal !

This is your new journal on electronics packaging and its related issues. The Japan Institute of Electronics Packaging (JIEP) has decided to publish the English journal in order to provide the information on Jisso technology that includes assembling, packaging, mounting and interconnection, and to share the new ideas for developing future devices with worldwide engineers and scientists. JIEP welcomes many contributions from Japanese engineers and scientists to the journal. The deadline of manuscripts for the second volume will be the end of July, 2009. We believe that the technology level on semiconductor assembling and packaging in Japan has been high so far, but Japanese are not good at making English presentations to overseas engineers. We have noticed that it is important for Japanese to send technical information on Jisso to the world over. Surely JIEP welcomes the submission of exciting papers from overseas countries. We hope that we can stimulate each other by sharing the state of art idea and technology through this journal. Finally, I would like to thank all the editors worked hard on this first publication.

December 25, 2008

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